

**THOMSON  
SEMICONDUCTORS**

**BTB 19 B**  
 UNINSULATED TRIACS  
 TRIACS NON ISOLÉS  
*T-25-15*

New range suited for applications such as phase control and static switching.  
 — Glass passivated chip.  
 —  $I_{GT}$  specified in four quadrants.

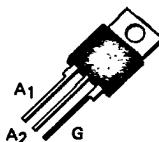
Nouvelle gamme adaptée à tous les types de fonctionnement : de la commutation statique au contrôle de phase.  
 — Pastille glassivée.  
 —  $I_{GT}$  défini dans les quatre quadrants.

$I_{TRMS} = 20 \text{ A}/T_c = 75^\circ\text{C}$

$V_{DRM} : 200 \text{ V} \rightarrow 700 \text{ V}^*$

$I_{GT} = 50 \text{ mA (Q I-II-III)}$   
 $100 \text{ mA (Q IV)}$

Case Boîtier : TO 220 AB plastic (CB-415)



ABSOLUTE RATINGS (LIMITING VALUES) VALEURS LIMITES ABSOLUES D'UTILISATION		Symbols	BTB 19 B		Units
RMS on-state current (360° conduction angle) <i>Courant efficace à l'état passant (angle de conduction 360°)</i>	$T_c = 75^\circ\text{C}$	$I_{TRMS}$	20		A
Non repetitive surge peak on-state current (on full cycle) at $25^\circ\text{C} < T_j \text{ initial} < 125^\circ\text{C}$ <i>Courant non répétitif de surcharge crête accidentelle à l'état passant (1 cycle complet) à <math>25^\circ\text{C} &lt; T_j \text{ initial} &lt; 125^\circ\text{C}</math></i>	$F = 60 \text{ Hz}$	$I_{TSM}$	188		A
	$F = 50 \text{ Hz}$		180		
$I_{2t}$ value <i>Valeur de la constante <math>I_{2t}</math></i>	$t = 10 \text{ ms}$	$I_{2t}$	162		A <sub>2s</sub>
Critical rate of rise of on-state current** <i>Vitesse critique de croissance du courant à l'état passant</i>	Repetitive $F = 60 \text{ Hz}$ Non Repetitive	di/dt	10		A/ $\mu\text{s}$
			60		
Storage and operating junction temperature range <i>Températures extrêmes de stockage et de jonction en fonctionnement</i>	$T_{stg}$ $T_j$		$-40 \rightarrow +150$ $-40 \rightarrow +125$		°C

ABSOLUTE RATING (LIMITING VALUE) VALEUR LIMITE ABSOLUE D'UTILISATION	Symbol	BTB19-200B	BTB19-400B	BTB19-600B	BTB19-700B	Unit
Repetitive peak off-state voltage <i>Tension de crête répétitive à l'état bloqué</i>	$V_{DRM}$	$\pm 200$	$\pm 400$	$\pm 600$	$\pm 700$	V

\*800 V on request  
800 V sur demande

\*\*Gate supply  
Générateur de gâchette : 20 V/20 Ω -  $t_r < 0,1 \mu\text{s}$  -

Half sine wave 6,3 μs  
Demi-sinusoidé de 6,3 μs -  $V_{DRM}$  specified  
spécifié

April 1984 - 1/4

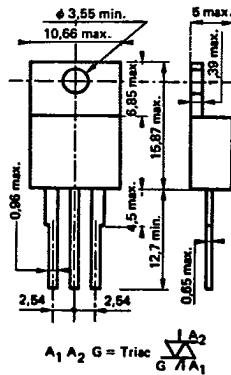
Thermal resistance Résistance thermique Junction to ambient - Junction - ambiante	Symbols	BTB 19 B	Units
	R <sub>th j-a</sub>	60	°C/W
Junction to case for DC - Junction - boîtier en continu	R <sub>th j-c DC</sub>	2,66	°C/W
Junction to case for 360° conduction angle (F = 50 Hz) - Junction - boîtier pour angle de conduction 360° (F = 50 Hz)	R <sub>th j-c AC</sub>	2	°C/W

## GATE CHARACTERISTICS (MAXIMUM VALUES)

## CARACTÉRISTIQUES DE GACHETTE (VALEURS MAXIMALES)

P<sub>GM\*</sub> = 40 W (t = 10 μs) P<sub>G(AV)</sub> = 1 W I<sub>GM\*</sub> = 4 A (t = 10 μs) V<sub>GM\*</sub> = 16 V (t = 10 μs)ELECTRICAL CHARACTERISTICS (T<sub>j</sub> = 25°C unless otherwise specified)CARACTÉRISTIQUES ELECTRIQUES (T<sub>j</sub> = 25°C sauf spécification contraire)

Symbols	Quadrants	Values			Units	Test conditions
		min.	typ.	max.		
I <sub>GT</sub>	I-II-III			50	mA	V <sub>D</sub> = 12 V R <sub>L</sub> = 33 Ω Pulse duration > 20 μs
	IV			100		V <sub>D</sub> = 12 V R <sub>L</sub> = 33 Ω Pulse duration > 20 μs
V <sub>GT*</sub>				2,5	V	T <sub>j</sub> = 125°C V <sub>D</sub> = V <sub>DRM</sub> R <sub>L</sub> = 3 kΩ Pulse duration > 20 μs
V <sub>GD*</sub>		0,2			V	
I <sub>H**</sub>				50	mA	V <sub>D</sub> = 12 V Gate open
I <sub>L</sub>	I-III-IV		50		mA	V <sub>D</sub> = 12 V R <sub>L</sub> = 33 Ω Pulse duration > 20 μs
	II		100			
V <sub>TM**</sub>				1,7	V	I <sub>TM</sub> = 28 A t <sub>p</sub> = 10 ms
I <sub>DRM**</sub>				0,1	mA	T <sub>j</sub> = 25°C
				1		T <sub>j</sub> = 125°C V <sub>DRM</sub> rated Gate open
(dv/dt)**		100	500		V/μs	T <sub>j</sub> = 125°C Gate open Linear slope up to 0,67 V <sub>DRM</sub>
(dv/dt) <sub>C**</sub>			10		V/μs	T <sub>c</sub> = 75°C (di/dt) <sub>C</sub> = 8,9 A/ms I <sub>TRMS</sub> and V <sub>DRM</sub> rated
t <sub>gt*</sub>				2	μs	dI <sub>G</sub> /dt = 3,5 A/μs I <sub>G</sub> = 500 mA I <sub>TRMS</sub> and V <sub>DRM</sub> rated

\* For either polarity of gate voltage with reference to electrode A<sub>1</sub>.\*\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>.CASE DESCRIPTION  
DESCRIPTION DU BOÎTIER

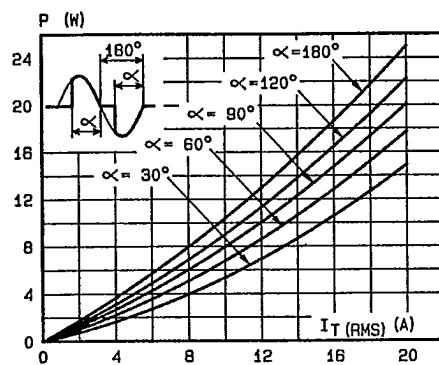


Fig.1 - Maximum mean power dissipation versus RMS on-state current.

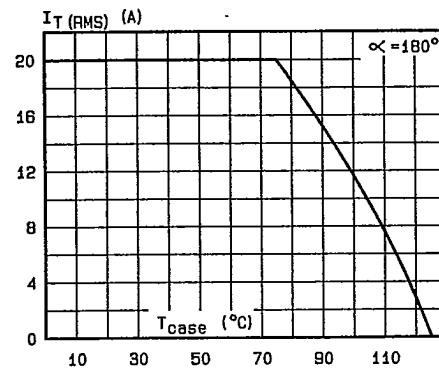


Fig.3 - RMS on-state current versus case temperature.

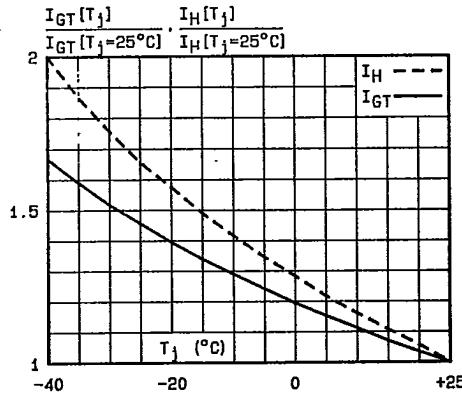


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

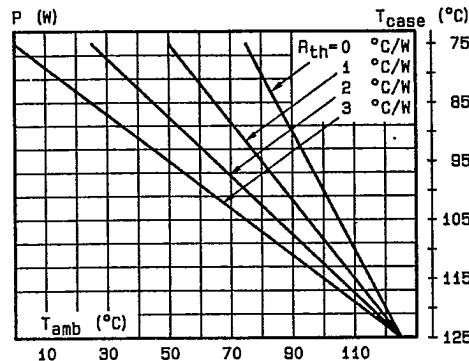


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (Tamb and Tcase) for different thermal resistances heatsink + contact.

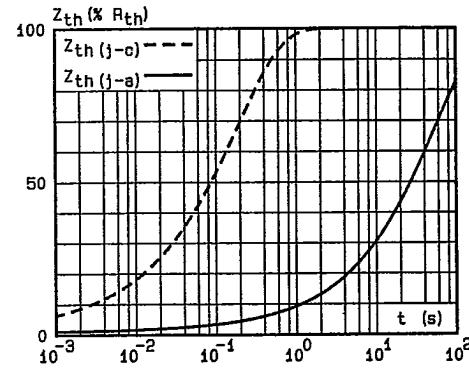


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

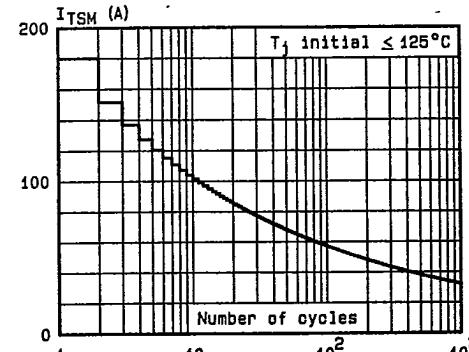


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

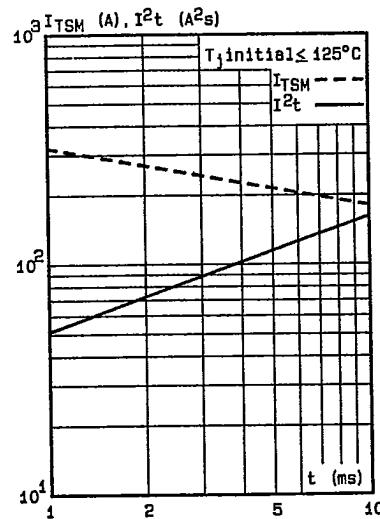
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Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width:  $t \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .

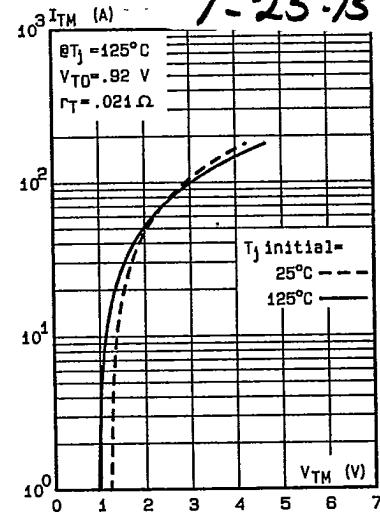


Fig.8 - On-state characteristic (maximum values).